

**DECLARATION AND POWER OF ATTORNEY FOR
PATENT APPLICATION**

As a below named inventor of this patent application titled,

**HEAT DISSIPATION INTERFACE
FOR SEMICONDUCTOR CHIP STRUCTURES**

I hereby declare:

That my residence, county, post office address and citizenship are as stated below next to my name and signature;

That I am the original and first inventor of the subject matter which is claimed in the above identified patent application;

I hereby acknowledge the duty to disclose information which is material to the patentability of the above identified patent application in accordance with Title 37 Code of Federal Regulations, Section 1.56;

I hereby state that I have reviewed and understand the contents of the above identified patent application, including the claims;

I hereby state that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code and that willful false statements may jeopardize the validity of the application or any patent issued thereon.

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That as a named inventor I hereby appoint the following attorney(s) and /or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

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Lawrence Shungwei Mok
Full name of inventor

Lawrence Shungwei Mok 2/20/2004
Inventor - Signature and date

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inventor - County and residence

USA
Inventor – Citizenship

Same as above
Inventor - Post Office Address

END OF DECLARATION